SHARP GP1S56T

# GP1S56T

#### ■ Features

1. High sensing accuracy (Slit width: 0.15mm)

2. Compact (Case height: 7.5mm)

3. With positioning pin

4. PWB direct mounting type

## Applications

1. Floppy disk drives

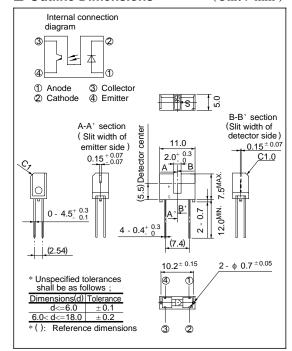
2. VCRs, cassette decks

3. Optoelectronic switches

## Compact, High Sensing Accuracy Type Photointerrupter with Positioning Pin

■ Outline Dimensions





## **■** Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$ 

	Parameter	Symbol	Rating	Unit	
Input	Forward current	$I_F$	50	mA	
	*1Peak forward current	$I_{FM}$	1	A	
	Reverse voltage	V <sub>R</sub>	6	V	
	Power dissipation	P	75	mW	
	Collector-emitter voltage	$V_{CEO}$	35	V	
Output	Emitter-collector voltage	$V_{ECO}$	6	V	
	Collector current	Ic	20	mA	
	Collector power dissipation	Pc	75	mW	
	Operating temperature	Topr	- 25 to + 85	°C	
Storage temperature		$T_{stg}$	- 40 to + 100	°C	
*2 Soldering temperature		$T_{sol}$	260	°C	

<sup>\*1</sup> Pulse width $\leq$ 100  $\mu$  s, Duty ratio = 0.01

<sup>\*2</sup> For 5 seconds

## **■** Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$ 

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage		V <sub>F</sub>	$I_F = 20 \text{mA}$	-	1.2	1.4	V
	Peak forward voltage		$V_{\text{FM}}$	$I_{FM} = 0.5A$	-	3	4	V
	Reverse current		$I_R$	$V_R = 3V$	-	-	10	μΑ
Output	Collector dark current		$I_{CEO}$	$V_{CE} = 20V$	-	1	100	nA
Transfer characteristics	Collector Current		Ic	$V_{CE} = 5V$ , $I_F = 20mA$	0.4	-	-	mA
	Collector-emitter saturation voltage		V <sub>CE(sat)</sub>	$I_F = 40mA$ $I_C = 0.25mA$	-	-	0.4	V
	Response time	Rise time	t <sub>r</sub>	$V_{CE} = 2V, I_{C} = 0.5mA$	-	38	90	μs
		Fall time	t <sub>r</sub>	$R_L = 1  K  \Omega$	-	48	110	μs

Fig. 1 Forward Current vs.

Ambient Temperature

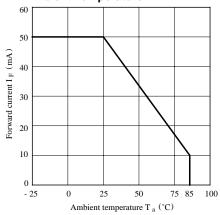


Fig. 3 Peak Forward Current vs. Duty Ratio

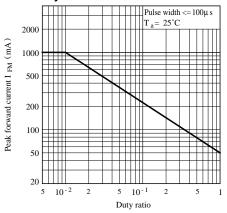


Fig. 2 Collector Power Dissipation vs.
Ambient Temperature

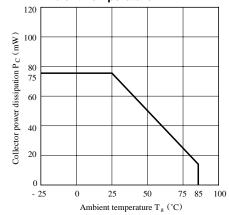


Fig. 4 Forward Current vs.

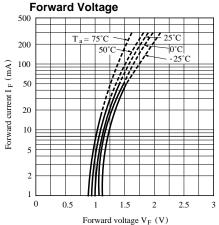


Fig. 5 Collector Current vs. Forward Current

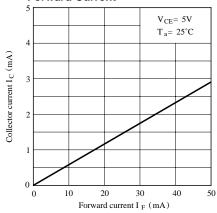


Fig. 7 Collector Current vs.

Ambient Temperature

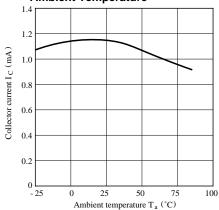


Fig. 9 Response Time vs.
Load Resistance

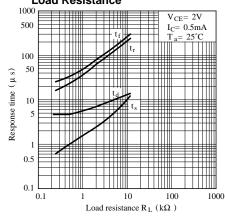


Fig. 6 Collector Current vs.
Collector-emitter Voltage

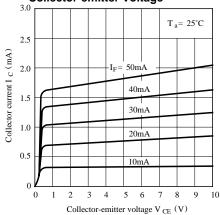
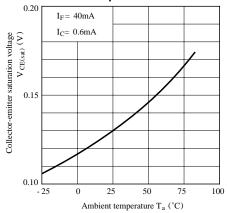


Fig. 8 Collector-emitter Saturation Voltage vs. Ambient Temperature



### **Test Circuit for Response Time**

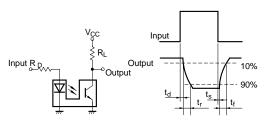


Fig.10 Frequency Response

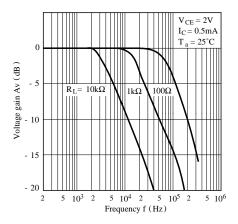


Fig.12 Relative Collector Current vs. Shield Distance (1)

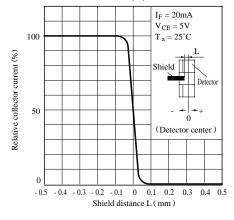


Fig.11 Collector Dark Current vs.
Ambient Temperature

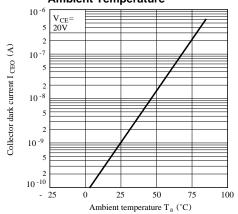
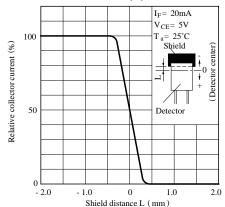


Fig.13 Relative Collector Current vs. Shield Distance (2)



#### ■ Precautions for Use

- (1) In case of cleaning, use only the following type of cleaning solvent. Ethyl alcohol, methyl alcohol, isopropyl alcohol
- (2) As for other general cautions, refer to the chapter "Precautions for Use".

#### **NOTICE**

- •The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.
- •Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.
- Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:
  - (i) The devices in this publication are designed for use in general electronic equipment designs such as:
  - Personal computers
  - Office automation equipment
  - Telecommunication equipment [terminal]
  - Test and measurement equipment
  - Industrial control
  - Audio visual equipment
  - Consumer electronics
  - (ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
  - Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
  - Traffic signals
  - Gas leakage sensor breakers
  - Alarm equipment
  - Various safety devices, etc.
  - (iii)SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
  - Space applications
  - Telecommunication equipment [trunk lines]
  - Nuclear power control equipment
  - Medical and other life support equipment (e.g., scuba).
- •Contact a SHARP representative in advance when intending to use SHARP devices for any "specific" applications other than those recommended by SHARP or when it is unclear which category mentioned above controls the intended use.
- •If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Control Law of Japan, it is necessary to obtain approval to export such SHARP devices.
- •This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.
- Contact and consult with a SHARP representative if there are any questions about the contents of this
  publication.